# imall

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## **Octal 3-State Non-Inverting Transparent Latch**

#### **High-Performance Silicon-Gate CMOS**

The MC74HC373A is identical in pinout to the LS373. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

These latches appear transparent to data (i.e., the outputs change asynchronously) when Latch Enable is high. When Latch Enable goes low, data meeting the setup and hold time becomes latched.

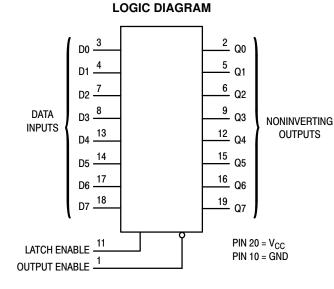
The Output Enable input does not affect the state of the latches, but when Output Enable is high, all device outputs are forced to the high-impedance state. Thus, data may be latched even when the outputs are not enabled.

The HC373A is identical in function to the HC573A which has the data inputs on the opposite side of the package from the outputs to facilitate PC board layout.

The HC373A is the non-inverting version of the HC533A.

#### Features

- Output Drive Capability: 15 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 µA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the JEDEC Standard No. 7.0 A Requirements
- Chip Complexity: 186 FETs or 46.5 Equivalent Gates
- These Devices are Pb-Free and are RoHS Compliant





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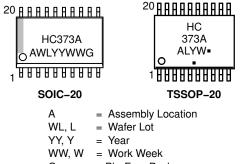


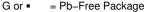
1330	P-20
DT SU	FFIX
CASE	948E

**PIN ASSIGNMENT** 

OUTPUT r			
ENABLE 9	1•	20 þ	V <sub>CC</sub>
Q0 🛛	2	19 🖡	Q7
	3	18 🛛	D7
D1 🛛	4	17	D6
Q1 🛛	5	16	Q6
Q2 🛛	6	15 🛛	Q5
D2 🛛	7	14 🏻	D5
D3 🛛	8	13	D4
Q3 🛛	9	12	Q4
GND 🛛	10	11 🏻	LATCH
· ·			ENABLE

#### **MARKING DIAGRAMS**





(Note: Microdot may be in either location)

FUNCTION TABLE						
	Inputs		Output			
Output	Latch					
Enable	Enable	D	Q			
Г	Н	Н	Н			
L	Н	L	L			
L	L	Х	No Change			
H X X Z						
X = Don't	Care					

Z = High Impedance

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

Design Criteria	Value	Units
Internal Gate Count*	46.5	ea
Internal Gate Propagation Delay	1.5	ns
Internal Gate Power Dissipation	5.0	μW
Speed Power Product	0.0075	рJ

\*Equivalent to a two-input NAND gate.

#### MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>in</sub>	DC Input Voltage (Referenced to GND)	–0.5 to V <sub>CC</sub> + 0.5	V
V <sub>out</sub>	DC Output Voltage (Referenced to GND)	–0.5 to V <sub>CC</sub> + 0.5	V
l <sub>in</sub>	DC Input Current, per Pin	±20	mA
I <sub>out</sub>	DC Output Current, per Pin	±35	mA
I <sub>CC</sub>	DC Supply Current, $V_{CC}$ and GND Pins	±75	mA
PD	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T <sub>stg</sub>	Storage Temperature	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (SOIC, SSOP or TSSOP Package)	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$ . Unused inputs must always be tied to an appropriate logic voltage

level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

+Derating: SOIC Package: -7 mW/°C from 65° to 125°C

TSSOP Package: -6.1 mW/°C from 65° to 125°C

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types	-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC} = 2.0$ (Figure 1) $V_{CC} = 4.5$ $V_{CC} = 6.0$	V 0	1000 500 400	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guar	anteed Lim	nit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	–55 to 25°C	≤ 85°C	≤ 125°C	Unit
VIH	Minimum High-Level Input	$V_{out} = V_{CC} - 0.1 V$	2.0	1.5	1.5	1.5	V
	Voltage	$ I_{out}  \le 20 \mu A$	3.0	2.1	2.1	2.1	
	-		4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
VIL	Maximum Low-Level Input	$V_{out} = 0.1 V$	2.0	0.5	0.5	0.5	V
	Voltage	$ I_{out}  \le 20 \mu A$	3.0	0.9	0.9	0.9	
	-		4.5	1.35	1.35	1.35	
			6.0	1.8	1.8	1.8	
V <sub>OH</sub>	Minimum High–Level Output	$V_{in} = V_{IH}$	2.0	1.9	1.9	1.9	V
	Voltage	$  _{out}  \le 20 \mu A$	4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	
		$V_{in} = V_{IH}$ $ I_{out}  \le 2.4 \text{ m}$	A 3.0	2.48	2.34	2.2	
		$ I_{out}  \le 6.0 \text{ m}$	A 4.5	3.98	3.84	3.7	
		$ I_{out}  \le 7.8 \text{ m}$	A 6.0	5.48	5.34	5.2	
V <sub>OL</sub>	Maximum Low-Level Output	$V_{in} = V_{IL}$	2.0	0.1	0.1	0.1	V
	Voltage	$ I_{out}  \le 20 \mu A$	4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	
		$V_{in} = V_{IL}$ $ I_{out}  \le 2.4 \text{ m}$	A 3.0	0.26	0.33	0.4	
		$ I_{out}  \le 6.0 \text{ m}$	A 4.5	0.26	0.33	0.4	
		I <sub>out</sub>   ≤ 7.8 m	A 6.0	0.26	0.33	0.4	
l <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	±0.1	±1.0	±1.0	μΑ
I <sub>OZ</sub>	Maximum Three-State	Output in High-Impedance State	6.0	±0.5	±5.0	±10	μΑ
02	Leakage Current	$V_{in} = V_{IL} \text{ or } V_{IH}$					
	-	$V_{out} = V_{CC}$ or GND					
Icc	Maximum Quiescent Supply	$V_{in} = V_{CC}$ or GND	6.0	4.0	40	160	μA
00	Current (per Package)	$I_{out} = 0 \mu A$					

#### **AC ELECTRICAL CHARACTERISTICS** ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6.0 \text{ ns}$ )

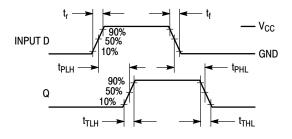
			Guar	anteed Lim	it	
Symbol	Parameter	V <sub>CC</sub> V	–55 to 25°C	≤ 85°C	≤ 125°C	Unit
t <sub>PLH</sub>	Maximum Propagation Delay, Input D to Q	2.0	125	155	190	ns
t <sub>PHL</sub>	(Figures 1 and 5)	3.0	80	110	130	l
		4.5	25	31	38	
		6.0	21	26	32	
t <sub>PLH</sub>	Maximum Propagation Delay, Latch Enable to Q	2.0	140	175	210	ns
t <sub>PHL</sub>	(Figures 2 and 5)	3.0	90	120	140	l
		4.5	28	35	42	
		6.0	24	30	36	
t <sub>PLZ</sub>	Maximum Propagation Delay, Output Enable to Q	2.0	150	190	225	ns
t <sub>PHZ</sub>	(Figures 3 and 6)	3.0	100	125	150	
		4.5	30	38	45	l
		6.0	26	33	38	
t <sub>PZL</sub>	Maximum Propagation Delay, Output Enable to Q	2.0	150	190	225	ns
t <sub>PZH</sub>	(Figures 3 and 6)	3.0	100	125	150	
		4.5	30	38	45	
		6.0	26	33	38	
t <sub>TLH</sub>	Maximum Output Transition Time, Any Output	2.0	60	75	90	ns
t <sub>THL</sub>	(Figures 1 and 5)	3.0	23	27	32	
		4.5	12	15	18	
		6.0	10	13	15	
C <sub>in</sub>	Maximum Input Capacitance		10	10	10	pF
C <sub>out</sub>	Maximum Three-State Output Capacitance		15	15	15	pF
	(Output in High-Impedance State)					
			Typical	@ 25°C, V <sub>C</sub>	c = 5.0 V	
Спр	Power Dissination Capacitance (Per Enabled Output)*		71	36	•	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Per Enabled Output)*				•	L

\* Used to determine the no-load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

#### **TIMING REQUIREMENTS** ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6.0 \text{ ns}$ )

					Guaranteed Limit					
			Vcc	–55 to	25°C	≤ <b>8</b>	5°C	≤ 12	25°C	
Symbol	Parameter	Figure	Volts	Min	Max	Min	Max	Min	Max	Unit
t <sub>su</sub>	Minimum Setup Time, Input D to Latch Enable	4	2.0 3.0 4.5 6.0	25 20 5.0 5.0		30 25 6.0 6.0		40 30 8.0 7.0		ns
t <sub>h</sub>	Minimum Hold Time, Latch Enable to Input D	4	2.0 3.0 4.5 6.0	5.0 5.0 5.0 5.0		5.0 5.0 5 0 5.0		5.0 5.0 5.0 5.0		ns
t <sub>w</sub>	Minimum Pulse Width, Latch Enable	2	2.0 3.0 4.5 6.0	60 23 12 10		75 27 15 13		90 32 18 15		ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times	1	2.0 3.0 4.5 6.0		1000 800 500 400		1000 800 500 400		1000 800 500 400	ns

#### SWITCHING WAVEFORMS





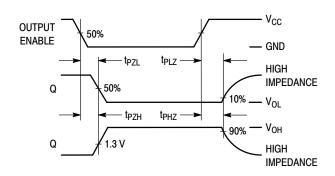


Figure 3.

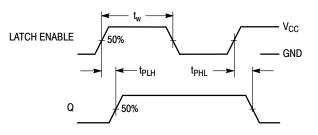
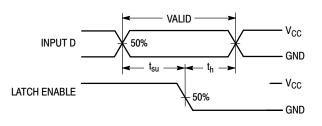
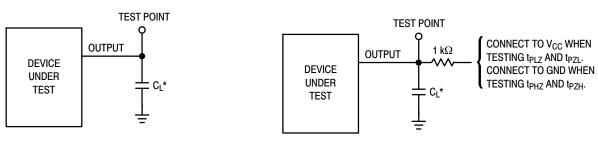


Figure 2.





#### **TEST CIRCUITS**



\*Includes all probe and jig capacitance

Figure 5.

\*Includes all probe and jig capacitance



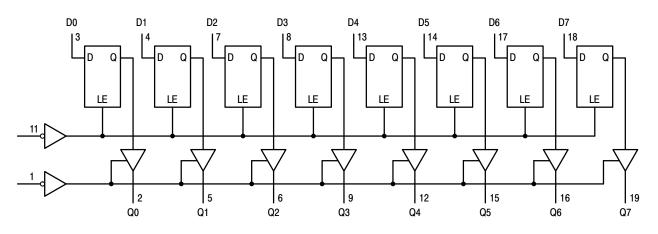


Figure 7. Expanded Logic Diagram

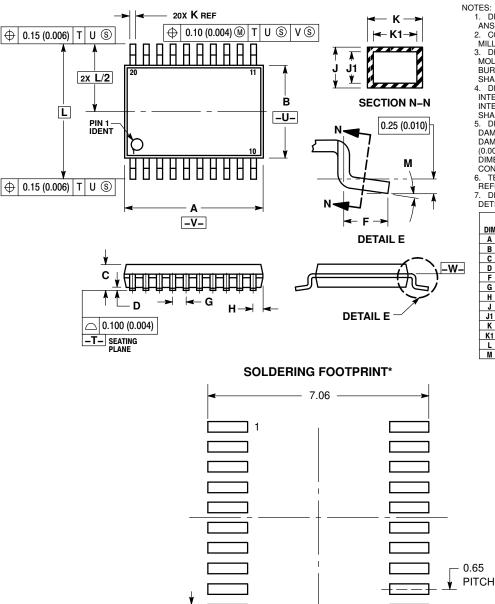
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74HC373ADWG	SOIC-20 WIDE (Pb-Free)	38 Units / Rail
MC74HC373ADWR2G	SOIC-20 WIDE (Pb-Free)	1000 Units / Reel
MC74HC373ADTG	TSSOP-20 (Pb-Free)	75 Units / Rail
MC74HC373ADTR2G	TSSOP-20 (Pb-Free)	2500 Units / Reel

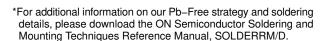
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

TSSOP-20 DT SUFFIX CASE 948E-02 **ISSUE C** 



16X 0.36 1



16X 1.26 A

DIMENSIONS: MILLIMETERS

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION

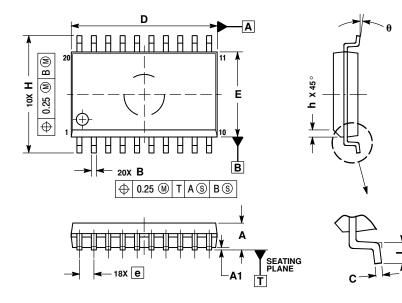
INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE. 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION

CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	6.40	6.60	0.252	0.260
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
н	0.27	0.37	0.011	0.015
ſ	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252	BSC
М	0°	8°	0°	8°

#### PACKAGE DIMENSIONS

SOIC-20 DW SUFFIX CASE 751D-05 ISSUE G



NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
  DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS			
DIM	MIN	MAX		
Α	2.35	2.65		
A1	0.10	0.25		
В	0.35	0.49		
C	0.23	0.32		
D	12.65	12.95		
Ε	7.40	7.60		
е	1.27	BSC		
Н	10.05	10.55		
h	0.25	0.75		
L	0.50	0.90		
θ	0 °	7 °		

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